



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

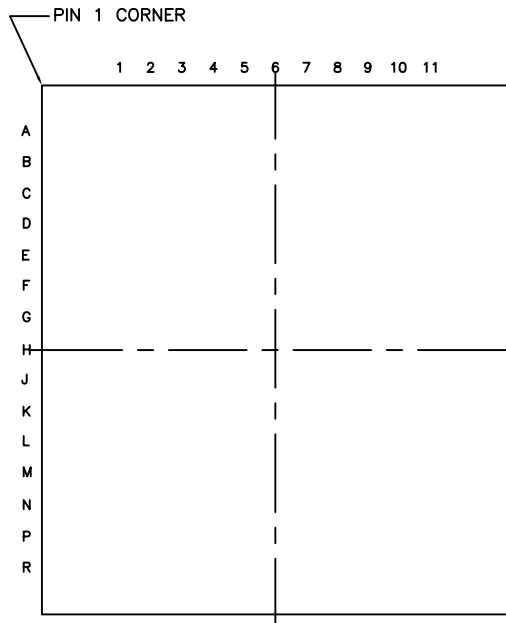
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

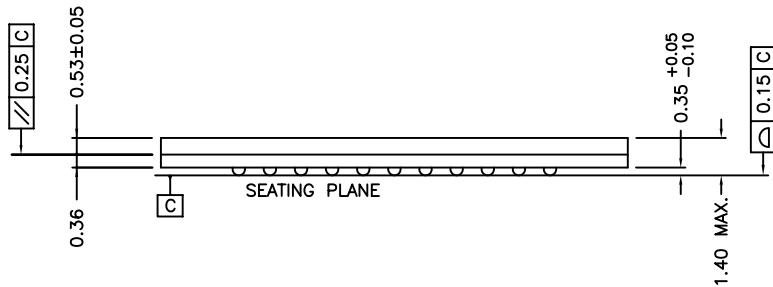
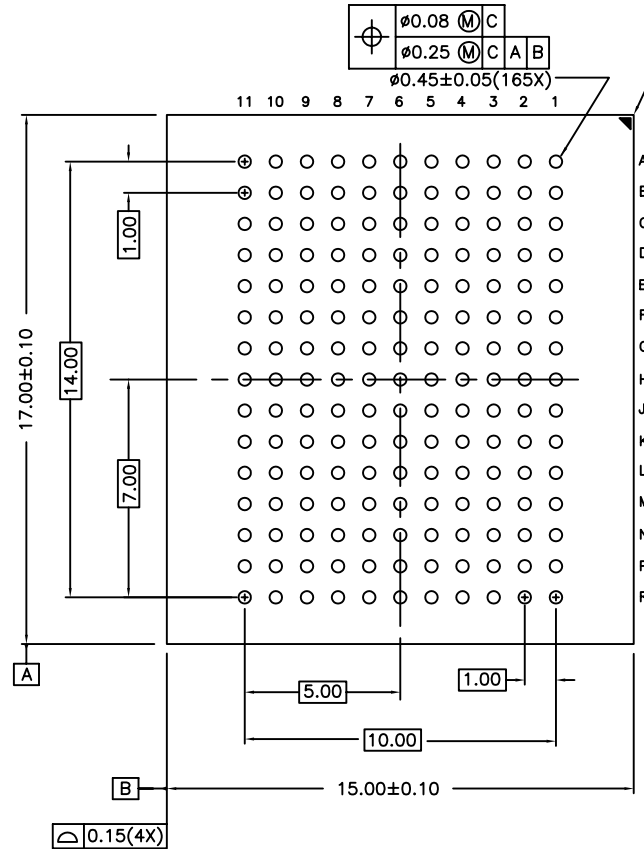
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

NOTES:
 SOLDER PAD TYPE: SOLDER MASK DEFINED (SMD)
 PACKAGE WEIGHT: 0.60g
 JEDEC REFERENCE: MO-216 / ISSUE E
 PACKAGE CODES: BBOAA / BW0AG

TOP VIEW



BOTTOM VIEW PIN 1 CORNER




CYPRESS Company Confidential		TITLE	
		PACKAGE OUTLINE, 16SLD FBGA 15X17X1.40MM (0.45 BALL DIAMETER)	
SPEC NO.		REV	
51-85165		*E	
SCALED TO FIT	N/A	SHEET 1 OF 2	

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PACKAGE CODE(S)

BBOAA
 BW0AG

REV.	ECN NO.	ORIGIN OF CHANGE	DESCRIPTION OF CHANGE
**	115878	—	NEW RELEASE
*A	129790	—	CHANGE SUBSTRATE THICKNESS, PKG. HEIGHT, LEAD COPLANARITY, BALL HEIGHT TOL., TITLE.
*B	2741152	—	CONVERTED TO STANDARD DRAWING FORMAT CHANGED POSITION TOLERANCE FROM 0.05 TO 0.08
*C	3278636	—	NO CHANGE. SUNSET REVIEW.
*D	3366875	—	Added Notes (SMD, weight, and Pack Codes) and Part No.
*E	4600008	XANC	FOR SUNSET REVIEW. UPDATE DRAWING TEMPLATE.

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TITLE PACKAGE OUTLINE, 16SLD FBGA 15X17X1.40MM (0.45 BALL DIAMETER)	
SPEC NO. 51-85165	REV *E
SCALED TO FIT N/A	SHEET 2 OF 2

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